

THOMSON SEMICONDUCTORS

TL 1003 → TL 8003
THYRISTORS
T-25-11

General purpose SCR suited for power supplies up to 400 Hz on resistive or inductive loads.

- $V_{DRM} = V_{RRM}$ up to 800 V.
- Glass passivated chip - High stability and reliability.
- High surge capability.

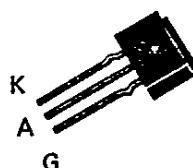
Thyristors à usage général pour des alimentations jusqu'à 400 Hz sur charges résistives ou inductives.

- $V_{DRM} = V_{RRM}$ jusqu'à 800 V.
- Pastille glassivée - Grande stabilité des caractéristiques.
- Courant de surcharge élevé.

$$I_T(\text{RMS}) = 1,6 \text{ A} / T_L = 50^\circ\text{C}$$

$$V_{DRM} \\ 100 \text{ V} < = < 800 \text{ V} \\ V_{RRM}$$

Case Boîtier : TL (CB-274) plastic



ABSOLUTE RATINGS (LIMITING VALUES) VALEURS LIMITES ABSOLUES D'UTILISATION	Symbol	Value	Unit
RMS on-state current* <i>Courant efficace à l'état passant*</i>	$I_T(\text{RMS})$	1,6 @ $T_L = 50^\circ\text{C}$	A
Mean on-state current* <i>Courant moyen à l'état passant*</i>	$I_T(\text{AV})$	1 @ $T_L = 50^\circ\text{C}$	A
Non repetitive surge peak on-state current** <i>Courant non répétitif de surcharge crête accidentelle à l'état passant**</i>	I_{TSM} I_{TSM}	73 (t = 8,3 ms) 70 (t = 10 ms) @ $T_j \leq 110^\circ\text{C}$	A
I^2t for fusing <i>Valeur de la constante I^2t</i>	I^2t	25 (t = 10 ms) @ $T_j \leq 110^\circ\text{C}$	A^2s
Critical rate of rise of on-state current*** <i>Vitesse critique de croissance du courant à l'état passant***</i>	di/dt	100	$\text{A}/\mu\text{s}$
Storage and operating junction temperatures <i>Températures extrêmes de stockage et de jonction en fonctionnement</i>	T_{stg} T_j	-40, +150 -40, +110	$^\circ\text{C}$

$@ T_j = 110^\circ\text{C}$	TL 1003	TL 2003	TL 4003	TL 6003	TL 8003
$V_{DRM} = V_{RRM}$ (V)	100	200	400	600	800

Thermal resistances Résistances thermiques	Symbol	Value	Unit
- Junction-leads <i>Jonction-connexions</i>	$R_{th(j-l)}$	35	$^\circ\text{C/W}$
- Junction-ambient on printed circuit (with Cu 1 cm ²) <i>Jonction-ambiente sur circuit imprimé (avec Cu 1 cm²)</i>	$R_{th(j-a)}$	50	$^\circ\text{C/W}$

*Single phase circuit, 180° conduction angle

*Circuit monophasé, angle de conduction 180°

***IGT = 100 mA $di/dt = 1 \text{ A}/\mu\text{s}$

**Half-sine wave
**Demi-onde sinusoïdale

May 1984 - 1/4

GATE CHARACTERISTICS (Maximum values)

CARACTÉRISTIQUES DE GACHETTE (Valeurs maximales)

$P_{GM} = 20 \text{ W}$ ($t = 10 \mu\text{s}$)

$P_{G(AV)} = 0,1 \text{ W}$

$I_{FGM} = 1 \text{ A}$ ($t = 10 \mu\text{s}$)

$V_{FGM} = 15 \text{ V}$ ($t = 10 \mu\text{s}$)

$V_{RGM} = 5 \text{ V}$

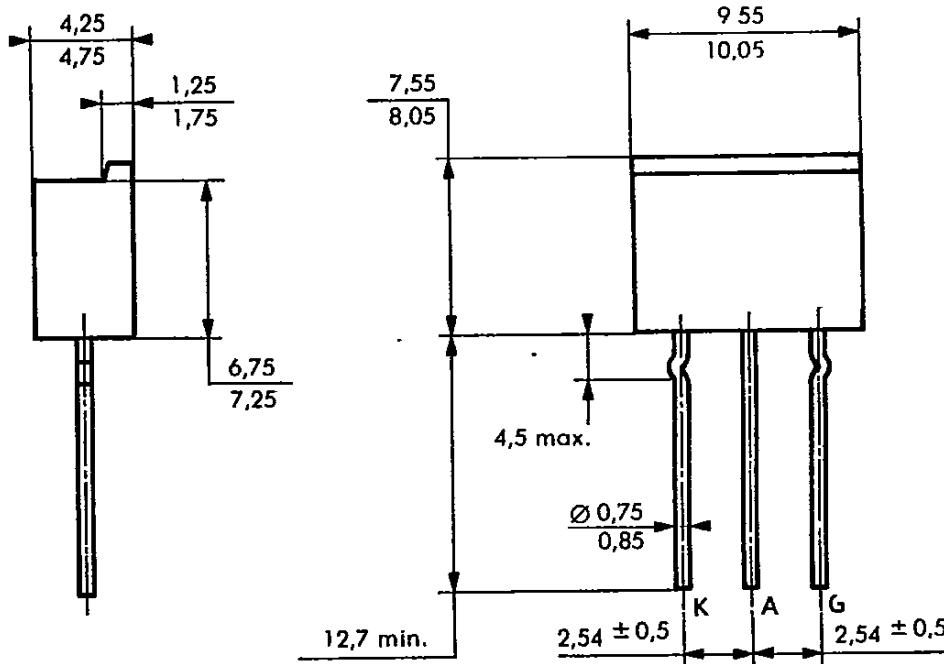
ELECTRICAL CHARACTERISTICS

CARACTÉRISTIQUES ELECTRIQUES

Symbol	Value			Unit	Test conditions			
	min	typ	max		$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	$t_p \geq 20 \mu\text{s}$
I_{GT}			15	mA				
V_{GT}		1,2	3	V	$T_j = 25^\circ\text{C}$	$V_D = 12 \text{ V}$	$R_L = 33 \Omega$	$t_p \geq 20 \mu\text{s}$
V_{GD}	0,2			V	$T_j = 110^\circ\text{C}$	$V_D = V_{DRM}$	$R_L = 3,3 \text{ k}\Omega$	
I_H		20		mA	$T_j = 25^\circ\text{C}$	$I_T = 100 \text{ mA}$	Gate open	
V_{TM}			1,8	V	$T_j = 25^\circ\text{C}$	$I_{TM} = 3,2 \text{ A}$	$t_p = 10 \text{ ms}$	
I_{DRM}			2	mA	$T_j = 110^\circ\text{C}$	V_{DRM} specified		
I_{RRM}			2	mA	$T_j = 110^\circ\text{C}$	V_{RRM} specified		
t_{gt}		1,5		μs	$T_j = 25^\circ\text{C}$ $I_G = 100 \text{ mA}$	$I_T = 3,2 \text{ A}$ $dI_G/dt = 1 \text{ A}/\mu\text{s}$	$V_D = V_{DRM}$	
t_q		80		μs	$T_j = 110^\circ\text{C}$ $dI_R/dt = 10 \text{ A}/\mu\text{s}$	$I_T = 1 \text{ A}$ $dv/dt = 20 \text{ V}/\mu\text{s}$	$V_R = 10 \text{ V}$	$V_D = 0,67 V_{DRM}$ Gate open
dv/dt^*		100		$\text{V}/\mu\text{s}$	$T_j = 110^\circ\text{C}$	Linear slope up to 0,67 V_{DRM} specified Gate open		

*For higher guaranteed values, please consult us.

CASE DESCRIPTION
DESCRIPTION DU BOITIER



Cooling method : by convection (method A)
Marking : type number
Weight : 0,8 g

TL (CB-274) plastic

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7.25-11

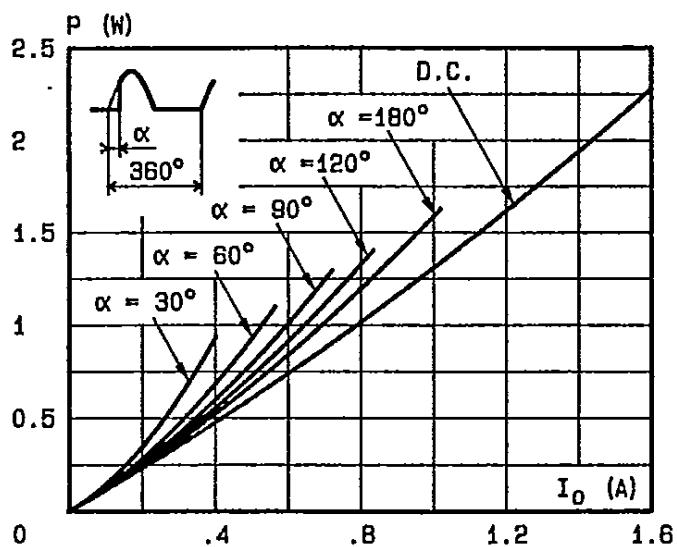


Fig.1 - Maximum mean power dissipation - versus mean on-state current.

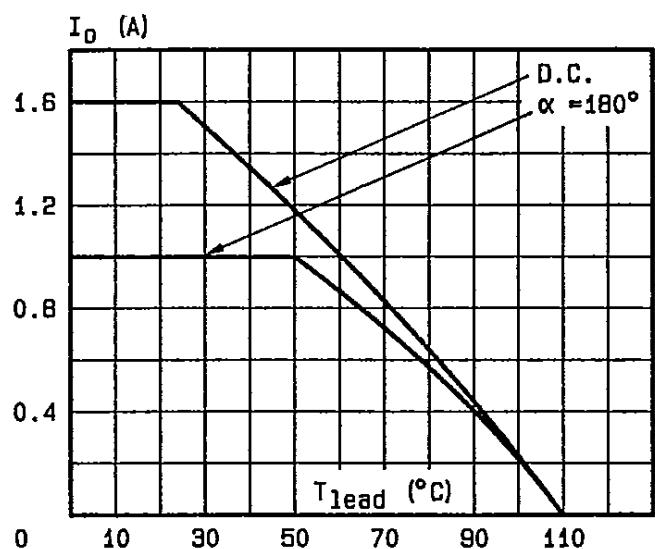


Fig.3 - Mean on-state current versus leads temperature.

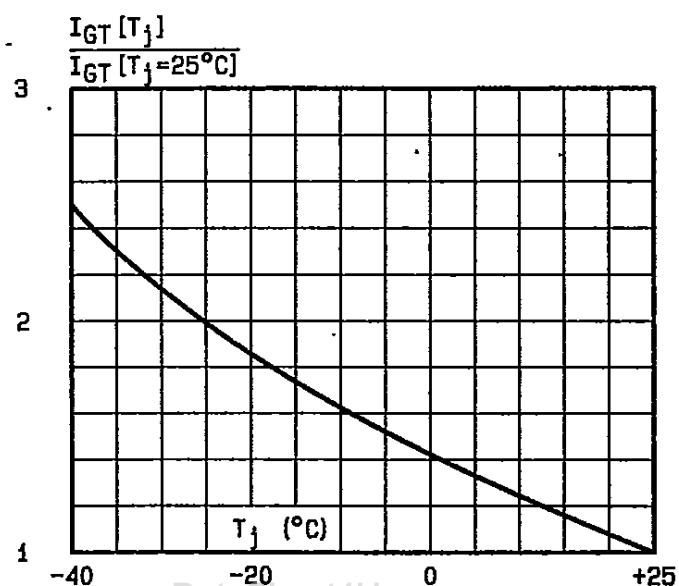


Fig.5 - Relative variation of gate trigger current versus junction temperature.

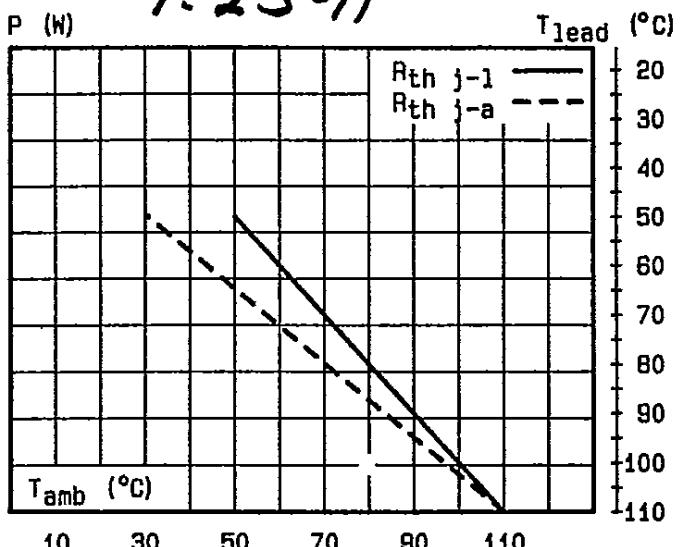


Fig.2 - Correlation between maximum mean power dissipation and maximum allowable temperatures (T_{amb} and T_{lead}).

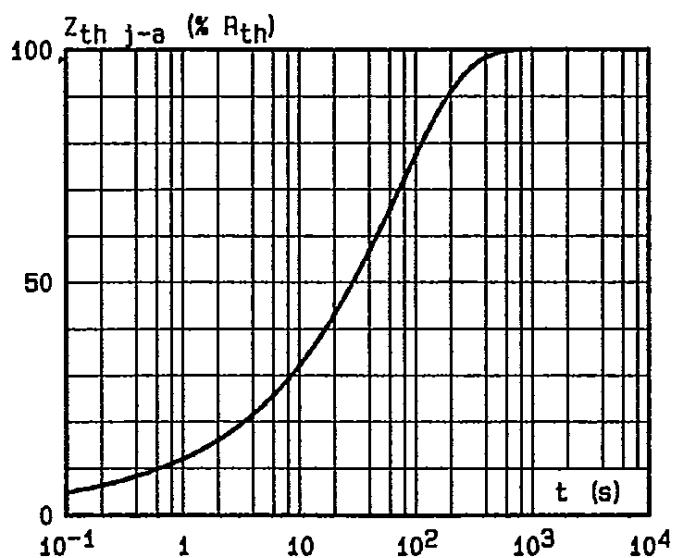


Fig.4 - Thermal transient impedance junction to ambient versus pulse duration.

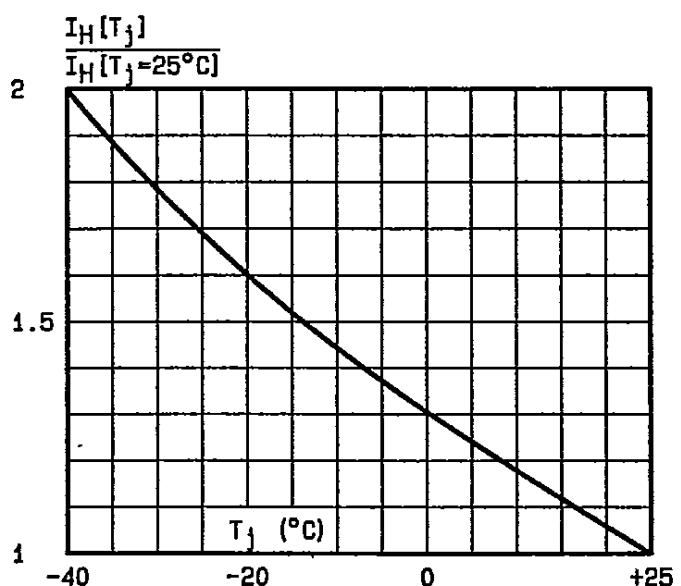


Fig.6 - Relative variation of holding current versus junction temperature.

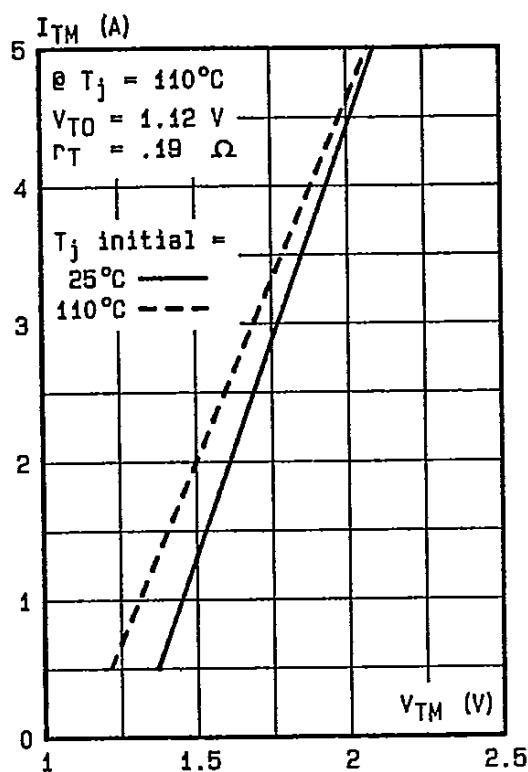


Fig.7 - On-state characteristics at low level (maximum values).

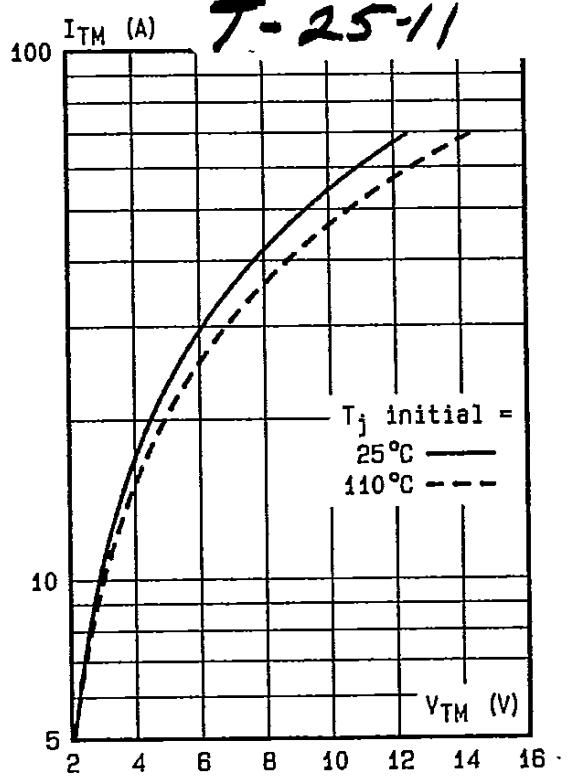


Fig.8 - On-state characteristics at high level (maximum values).

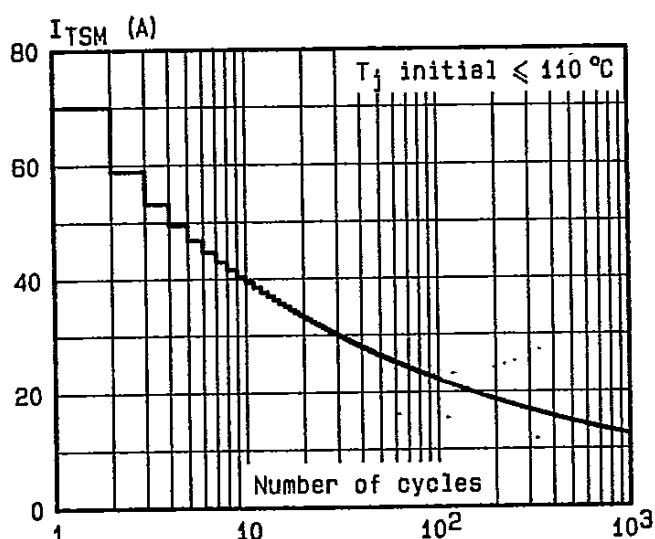


Fig.9 - Non repetitive surge peak on-state current versus number of cycles.

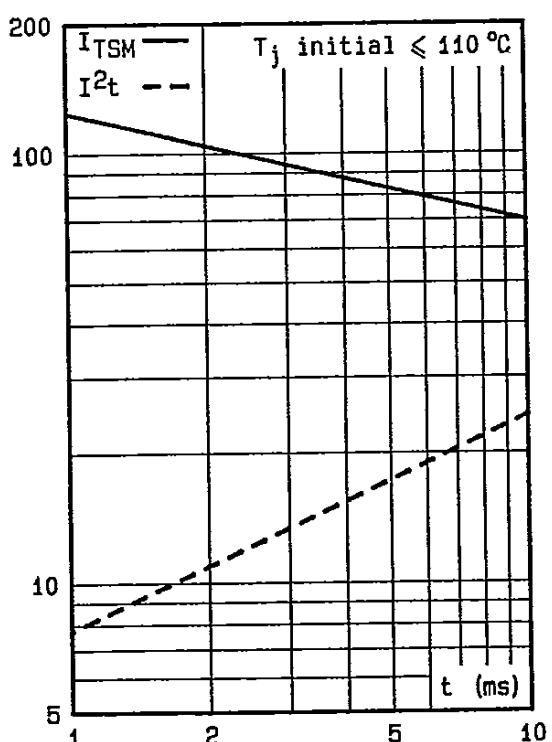


Fig.10 - Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .